12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130326000
Transfer of select devices in the .35um-UMC-F8J process to UMC-F8E Wafer Fab Facility
Change Notification / Sample Request

Date: 3/28/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130326000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
PCM1606E	null
PCM1606EG4	null
PCM1742E	null
PCM1742EG4	null
PCM1742KE	null
PCM1748E	null
PCM1748KE	null
PCM1753DBQ	null
PCM1754DBQ	null
PCM1754DBQG4	null
PCM1754DBQR	null
PCM1755DBQ	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20130326000	**PCN Date:**	03/28/2013
Title:	Transfer of select devices in the .35um-UMC-F8J process to UMC-F8E Wafer Fab Facility		
Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	06/28/2013	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☒	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the transfer of select devices in the .35um-UMC-F8J process to UMC-F8E Wafer Fab Facility.

Currently Qualified Sites, process, wafer dia.	**Additional Sites, process, wafer dia.**
UMC-F8J, .35um-UMC-F8J Process, 200mm	**UMC-F8E, 0.35 DPQM Process, 200mm**

Reason for Change:

Continuity of supply due to site shutdown

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
UMC-F8J	U8J	JPN

New

Chip Site	Chip site code (20L)	Chip country code (21L)
UMC-F8E	U8E	TWN

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

PCM1606E	PCM1742EG4	PCM1748KE/2KG4	PCM1754DBQG4
PCM1606E/2K	PCM1742KE	PCM1748KEG4	PCM1754DBQR
PCM1606E/2KG4	PCM1742KE/2K	PCM1753DBQ	PCM1754DBQRG4
PCM1606EG	PCM1742KE/2KG4	PCM1753DBQG4	PCM1755DBQ
PCM1606EG/2K	PCM1742KEG4	PCM1753DBQR	PCM1755DBQG4
PCM1606EG/2KE6	PCM1748E	PCM1753DBQR-S2	PCM1755DBQR
PCM1606EG4	PCM1748E/2K	PCM1753DBQR-S2G4	PCM1755DBQR/2354
PCM1606EGE6	PCM1748E/2KG4	PCM1753DBQRG4	PCM1755DBQRG4
PCM1742E	PCM1748EG4	PCM1754DBQ	
PCM1742E/2K	PCM1748KE	PCM1754DBQ-P	
PCM1742E/2KG4	PCM1748KE/2K	PCM1754DBQ-PG4	

Qualification Plan:

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device 1: PCM1753TDBQRQ1

Wafer Fab Site:	UMC-F8E	Wafer Fab Process:	0.35 DPTM
Wafer Diameter:	200mm		

Qualification Schedule:	**Start:** 03/2013	**End:**	End of 06/2013

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fails Lot#1	 Lot#2	 Lot#3
High Temp Operating Life	140C(480 Hrs)	77/0	77/0	77/0
Electrical Characterization	-	Comp	Comp	Comp
**High Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cycles)	77/0	77/0	77/0
ESD CDM	250V	3/0	3/0	3/0
ESD HBM	1000V	3/0	3/0	3/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
Die Shear	-	10/0	10/0	10/0
Latch-up	(Per JESD78)	6/0	6/0	6/0

** Preconditioning sequence: (Level 3/260C)

Qualification Device 2: PCM3168ATPAPRQ1

Wafer Fab Site:	UMC-F8E	Wafer Fab Process:	0.35 DPTM
Wafer Diameter:	200mm		

Qualification: ☒ **Plan** ☐ **Test Results**

Reliability Test	Conditions	Sample Size/Fails Lot#1	 Lot#2	 Lot#3
High Temp Operating Life	125C(1000 Hrs)	77/0	77/0	77/0
Electrical Characterization	–	Comp	Comp	Comp
**High Temp. Storage Life	150C(1000Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cycles)	77/0	77/0	77/0
ESD CDM	250V	3/0	3/0	3/0
ESD HBM	1000V	3/0	3/0	3/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
Die Shear	-	10/0	10/6	10/0
Latch-up	(Per JESD78)	6/0	6/0	6/0

** Preconditioning sequence: (Level 3/260C)

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com